



5x7mm Precision TCXO Model DV75C

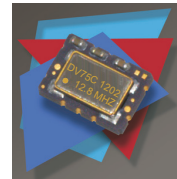


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Description:

The Connor-Winfield's DV75C is a 5x7mm Surface Mount Temperature Compensated Crystal Controlled Oscillator (TCXO) with LVCMOS output. Through the use of Analog Temperature Compensation the DV75C is capable of holding sub 1-ppm stabilities over the -40 to 85°C temperature range. The DV75C meets STRATUM 3 requirements.



Features:

- 3.3 Vdc Operation
- LVCMOS Output
- Frequency Stability: ± 0.28 ppm
- Temperature Range: -40 to 85°C
- Low Jitter <1ps RMS
- 5x7mm Surface Mount Package
- Tape and Reel Packaging
- RoHS Compliant / Pb Free

Applications:

- IEEE 1588 Applications
- Synchronous Ethernet slave clocks, ITU-T G.8262 EEC options 1 & 2
- Compliant to Stratum 3, GR-1244-CORE, GR-253-CORE & ITU-T-G.812 Type IV
- Wireless Communications
- Small Cells
- Test and Measurement

Absolute Maximum Ratings

Parameter	Minimum	Nominal	Maximum	Units	Notes
Storage Temperature	-55	-	85	°C	
Supply Voltage (Vcc)	-0.5	-	6.0	Vdc	
Input Voltage	-0.5	-	Vcc+0.5	Vdc	

Operating Specifications

Parameter	Minimum	Nominal	Maximum	Units	Notes
Nominal Frequencies (Fo) available	10.0, 12.8, 20.0, 25.0 and 40.0			MHz	
Frequency Calibration @ 25 °C	-1.0	-	1.0	ppm	1
Frequency Stability vs. Temperature	-0.28	-	0.28	ppm	2
Holdover Stability (Over 24 Hours)	-0.32	-	0.32	ppm	3
Frequency vs. Load Stability	-0.05	-	0.05	ppm	$\pm 5\%$
Frequency vs. Voltage Stability	-0.05	-	0.05	ppm	$\pm 5\%$
Static Temperature Hysteresis	-	-	0.4	ppm	4
Total Frequency Tolerance:	-4.6	-	4.6	ppm	5
Operating Temperature Range:	-40	-	85	°C	
Supply Voltage (Vcc)	3.135	3.3	3.465	Vdc	$\pm 5\%$
Supply Current (Icc)	-	-	6	mA	
Period Jitter	-	3	5	ps rms	
Integrated Phase Jitter	-	0.5	1.0	ps rms	6
Typical Phase Noise Fo = 10.0 MHz					
SSB Phase Noise at 10Hz offset	-	-99	-	dBc/Hz	
SSB Phase Noise at 100Hz offset	-	-122	-	dBc/Hz	
SSB Phase Noise at 1KHz offset	-	-145	-	dBc/Hz	
SSB Phase Noise at 10KHz offset	-	-152	-	dBc/Hz	
SSB Phase Noise at 100KHz offset	-	-153	-	dBc/Hz	
Start-up Time	-	-	10	ms	

LVCMOS Output Characteristics

Parameter	Minimum	Nominal	Maximum	Units	Notes
Load	-	15	-	pF	7
Voltage (High) (Voh)	90%Vcc	-	-	Vdc	
(Low) (Vol)	-	-	10%Vcc	Vdc	
Duty Cycle at 50% of Vcc	45	50	55	%	
Rise / Fall Time 10% to 90%	-	-	8	ns	

Notes:

1. Initial calibration @ 25°C. Specifications at time of shipment after 48 hours of operation.
2. Frequency stability vs. change in temperature. $[(F_{max} - F_{min}) / (2 * F_0)]$.
3. Inclusive of frequency stability, supply voltage change ($\pm 1\%$), load change, aging, for 24 hours.
4. Frequency change after reciprocal temperature ramped over the operating range. Frequency measured before and after at 25°C.
5. Inclusive of calibration @ 25°C, frequency vs. change in temperature, change in supply voltage ($\pm 5\%$), load change ($\pm 5\%$), reflow soldering process and 20 years aging, referenced to Fo
6. BW = 12 KHz to Fo/2 MHz.
7. For best performance it is recommended that the circuit connected to this output should have an equivalent input capacitance of 15pF.



Package Characteristics

Package: Hermetically sealed crystal mounted on a ceramic package

Environmental Characteristics

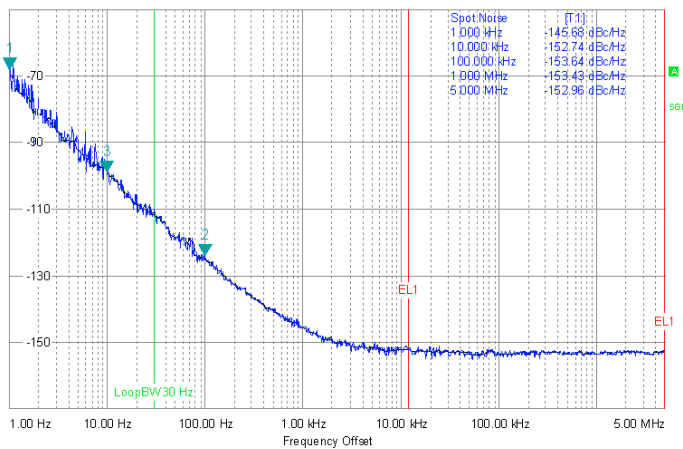
Vibration: Vibration per Mil Std 883E Method 2007.3 Test Condition A
Shock: Mechanical Shock per Mil Std 883E Method 2002.4 Test Condition B.
Soldering Process: RoHS compliant lead free. See soldering profile on page 3.

Ordering Information

DV75C-010.0M, DV75C-012.8M, DV75C-020.0M, DV75C-025.0M, DV75C-040.0M

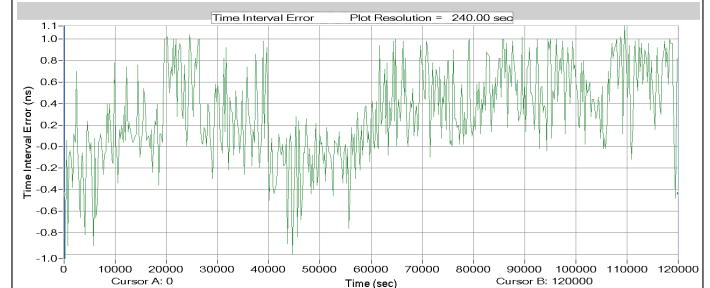
Phase Noise Information

Typical Phase Noise for DV75C-010.0M



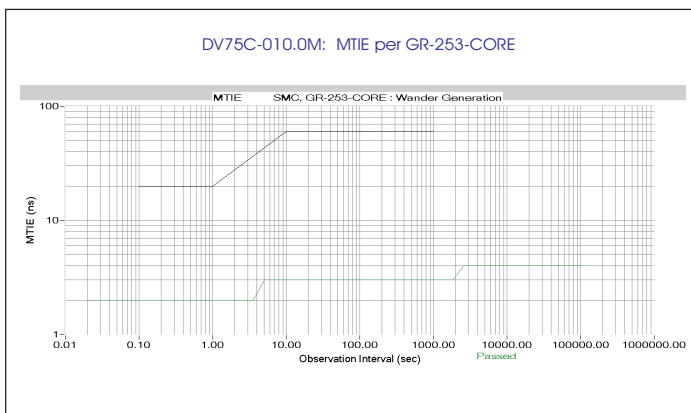
TIE

DV75C-010.0M: WANDER GENERATION IN A STRATUM 3 PLL AT 0.098 Hz BANDWIDTH



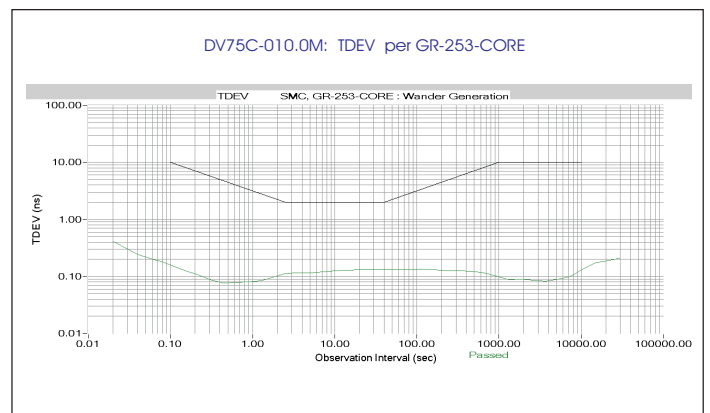
MTIE

DV75C-010.0M: MTIE per GR-253-CORE



TDEV

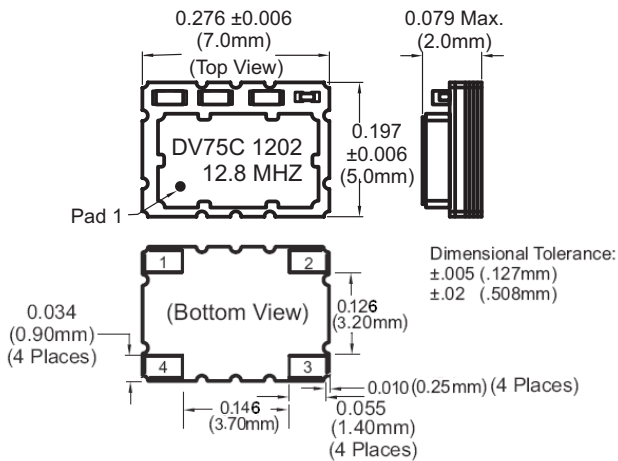
DV75C-010.0M: TDEV per GR-253-CORE



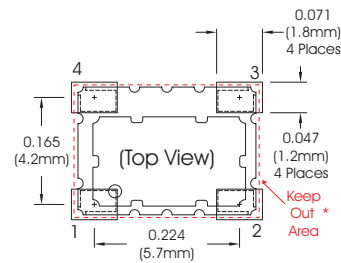


Package Layout

Applies to all frequencies except for 40.0MHz



Suggested Pad Layout



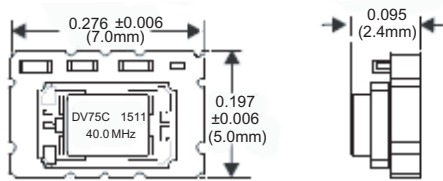
* Do not route any traces in the keep out area. It is recommended the next layer under the keep out area is to be ground plane.

Pad Connections

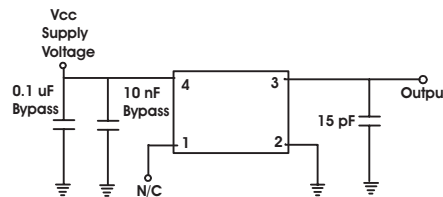
1:	N/C
2:	Ground
3:	Output (Fo)
4:	Supply Voltage (Vcc)

Alternate Package Layout

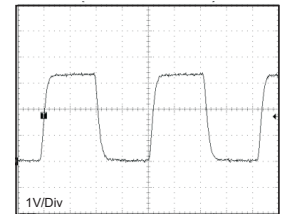
Applies to 40.0MHz frequency only.



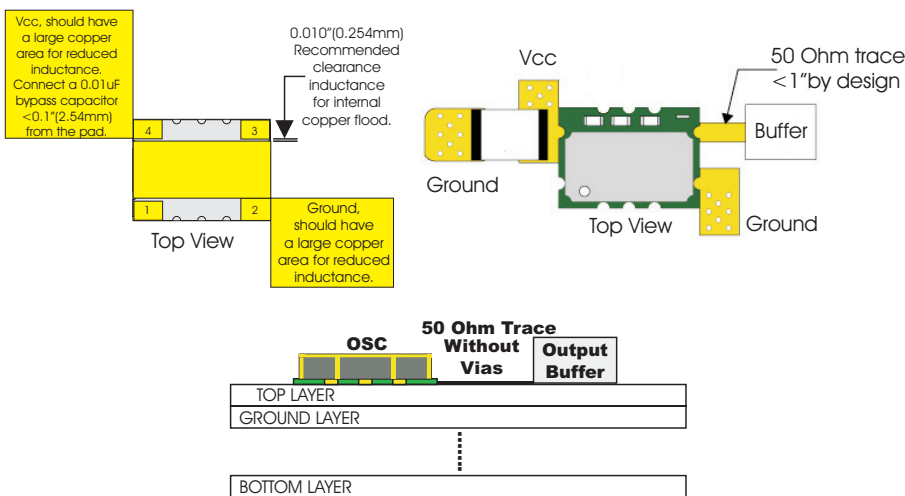
Test Circuit



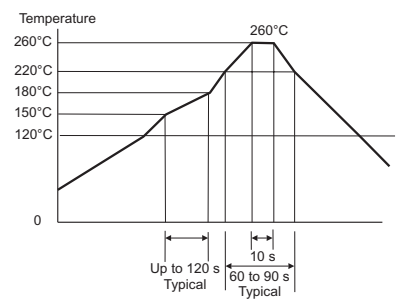
Output Waveform



Design Recommendations



Solder Profile

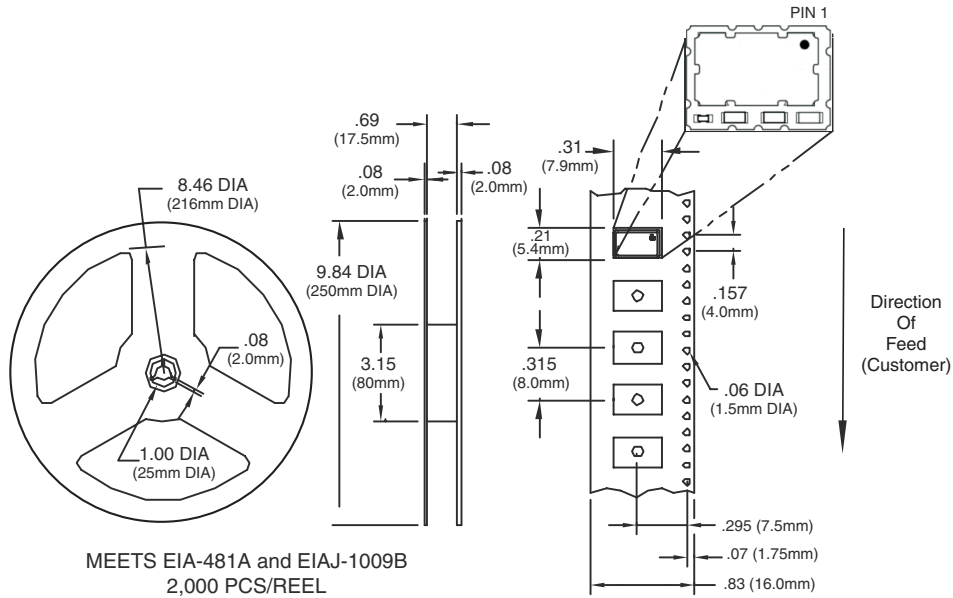


Meets IPC/JEDEC J-STD-020C

Attention: To achieve optimal frequency stability, and in some cases to meet the specification stated on this data sheet, it is required that the circuit connected to this TCXO output must have the equivalent input capacitance that is specified by the nominal load capacitance. Deviations from the nominal load capacitance will have a graduated effect on the stability of approximately 20 ppb per pF load difference.

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Tape and Reel Dimensions



Revision History

Revision	Date	Note
00	01/11/12	Data sheet released
01	11/26/12	Removed tri-state information from features and description.
02	04/15/13	Added "Applications", Phase noise, TIE, MTIE and TDEV plots.
03	12/03/13	Removed TR information from Ordering Information.
04	04/01/15	Add frequencies and update to Phase Noise Plot and Operating Specs
05	11/01/16	Clarify frequencies to which alternate package height applies, and added dimensions to bottom view.
06	11/10/16	Update Static Temperature Hysteresis note and Soldering Process information.

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